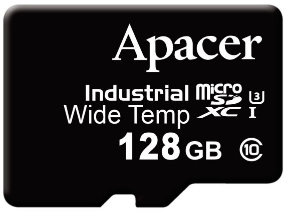

Model	Industrial microSD H1-M
Interface	SD 3.0
Connector	
Form Factor	microSD
Operation Mode	
Transfer Mode	
NAND Flash Type	MLC
Capacity	4G~128G
External DRAM	
Sequential Read Performance (MB/sec)	Up to 75
Sequential Write Performance (MB/sec)	Up to 65
ECC Engine	Built-in 42-bit per 1K bytes BCH ECC
IOPS (4K Random Write)	
Standard Operating Temperature (°C)	-25 ~ + 85
Extended Operating Temperature (°C)	-40 ~ + 85
Storage Temperature (°C)	-40 ~ + 85
Housing	
H/W Write Protect	
Screw Hole	
Cable-less Solution	
Thermal Sensor	
Shock	(Operating)1,500G, 0.5ms
Vibration	20Hz~80Hz/1.52mm (frequency/displacement) 80Hz~2,000Hz/20G (frequency/accelerate)
Operating Voltage	2.7V ~ 3.6V
Power Consumption	Active mode: 155mA & Idle mode: 445 uA
Dimension (L x W x H)	15x11x1 (mm)
MTBF (hours)	>3,000,000